TOSHIBA 2SK2837

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE (π -MOS V)

2 S K 2 8 3 7

HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE **APPLICATIONS**

Low Drain-Source ON Resistance : $R_{DS(ON)} = 0.21\Omega$ (Typ.)

High Forward Transfer Admittance : $|Y_{fs}| = 17S$ (Typ.)

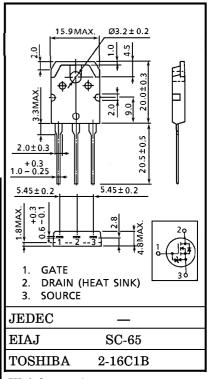
Low Leakage Current : I_{DSS}=100μA (Max.) (V_{DSS}=500V)

Enhancement-Mode : $V_{th} = 2.0 \sim 4.0 \text{V} \text{ (V}_{DS} = 10 \text{V}, I_D = 1 \text{mA)}$

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERIST	SYMBOL	RATING	UNIT	
Drain-Source Voltage	$V_{ m DSS}$	500	V	
Drain-Gate Voltage (R _{GS} =20kΩ)		$v_{ m DGR}$	500	V
Gate-Source Voltage	V_{GSS}	±30	V	
Durin Comment	DC	$I_{\mathbf{D}}$	20	A
Drain Current	Pulse	$I_{ m DP}$	80	A
Drain Power Dissipation	P_{D}	150	W	
Single Pulse Avalanche	EAS	960	mJ	
Avalanche Current	I_{AR}	20	A	
Repetitive Avalanche En	$\mathbf{E}_{\mathbf{A}\mathbf{R}}$	15	mJ	
Channel Temperature	$\mathrm{T_{ch}}$	150	°C	
Storage Temperature Range		$T_{ m stg}$	-55~150	$^{\circ}\mathrm{C}$

INDUSTRIAL APPLICATIONS Unit in mm



Weight: 4.6g

THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL		
Thermal Resistance, Channel to Case	R _{th (ch-c)}	0.833	°C/W
Thermal Resistance, Channel to Ambient	R _{th (ch-a)}		°C/W

Note;

- * Repetitive rating; Pulse Width Limited by Max. junction temperature.
- ** V_{DD} =90V, Starting T_{ch} =25°C, L=4.08mH R_G =25 Ω , I_{AR} =20A

This transistor is an electrostatic sensitive device. Please handle with caution.

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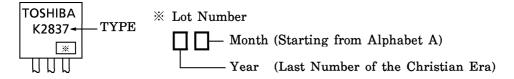
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

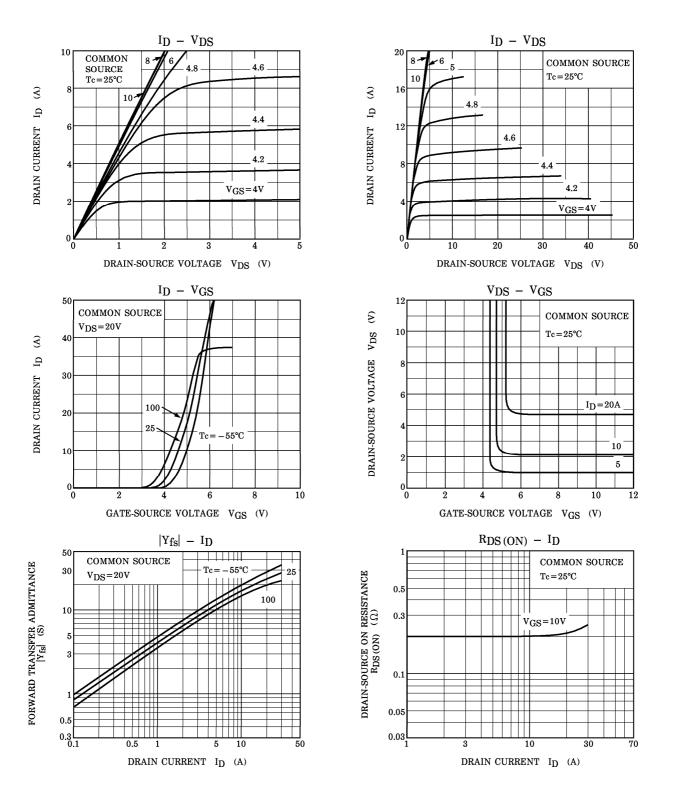
CHARACT	ERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage C	urrent	I_{GSS}	$V_{GS} = \pm 25V, V_{DS} = 0V$	_	_	±10	μ A
Gate-Source Breakdown Volt	age	V _(BR) GSS	$I_G = \pm 10 \mu A, V_{DS} = 0 V$	±30	_	_	V
Drain Cut-off Cu	arrent	$I_{ m DSS}$	V_{DS} =500V, V_{GS} =0V	_	_	100	μ A
Drain-Source Breakdown Volt	age	V _(BR) DSS	$I_D=10$ mA, $V_{GS}=0$ V	500	_	_	V
Gate Threshold	Voltage	$ m v_{th}$	$V_{\mathrm{DS}} = 10 \mathrm{V}, \ \mathrm{I_D} = 1 \mathrm{mA}$	2.0		4.0	V
Drain-Source ON	N Resistance	R _{DS} (ON)	$V_{GS} = 10V$, $I_D = 10A$	l —	0.21	0.27	Ω
Forward Transfe	r Admittance	Y _{fs}	$V_{DS} = 10V, I_{D} = 10A$	10	17	_	S
Input Capacitan	Input Capacitance		101/ 1/ 01/	_	3720	_	pF
Reverse Transfer Capacitance		$\mathrm{C}_{\mathrm{rss}}$	$V_{DS} = 10V, V_{GS} = 0V,$ f = 1MHz	_	340	_	
Output Capacita	nce	C_{oss}		_	1165	_	
Switching Time	Rise Time	t_r	$V_{GS} = \begin{bmatrix} 10V & I_{D} = 10A \\ 0V & V_{OUT} \\ R_{L} = \\ 20\Omega \end{bmatrix}$		30	_	
	Turn-on Time	t _{on}		_	70	_	na
	Fall Time	t_f		_	50	_	ns
	Turn-off Time	t _{off}	$V_{ ext{IN}}: t_{ ext{r}}, t_{ ext{f}} < 5 ext{ns}, \ ^{ ext{VDD}} = 200 ext{V}$ $\text{Duty} \leq 1\%, t_{ ext{w}} = 10 \mu ext{s}$	_	290	_	
Total Gate Charge (Gate-Source Plus Gate-Drain)		$\mathbf{Q}_{\mathbf{g}}$	V _{DD} ≒400V, V _{GS} =10V,	_	80	_	" _C
Gate-Source Charge		$\mathbf{Q}_{\mathbf{g}\mathbf{s}}$	$I_{D}=6A$		48	_	nC
Gate-Drain ("Miller") Charge		\mathbf{Q}_{gd}		_	32	_	

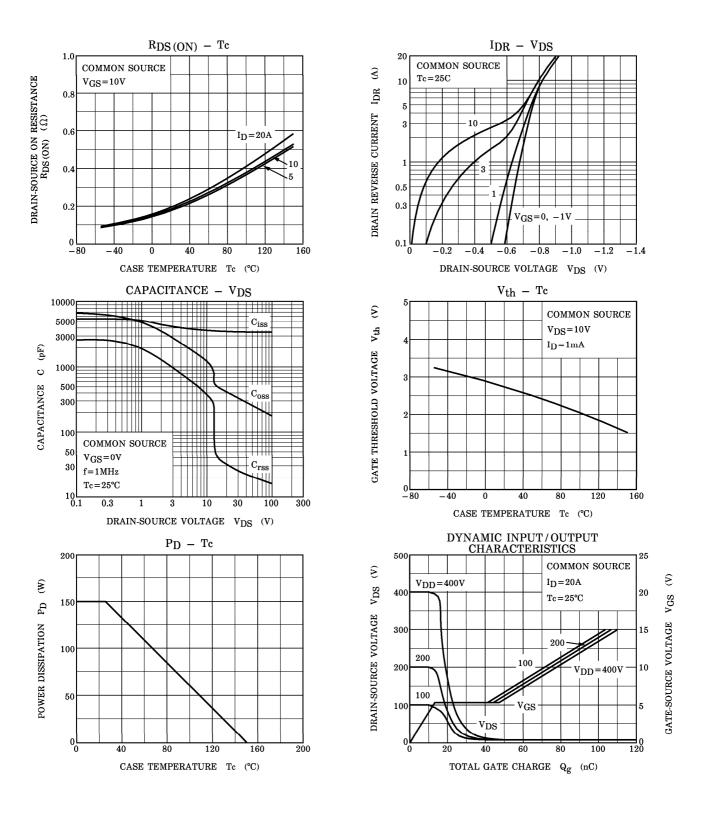
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

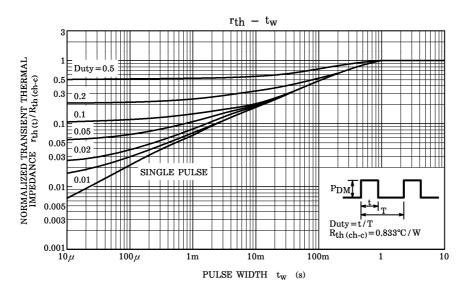
CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	$I_{ m DR}$	_	_	_	20	A
Pulse Drain Reverse Current	$I_{ m DRP}$	_	_	_	80	Α
Diode Forward Voltage	$v_{ m DSF}$	I_{DR} =20A, V_{GS} =0V	_	_	-1.7	V
Reverse Recovery Time	t _{rr}	I_{DR} =20A, V_{GS} =0V	_	540	_	ns
Reverse Recovery Charge	Q_{rr}	$dI_{DR}/dt = 100A/\mu s$	_	5.4	_	μ C

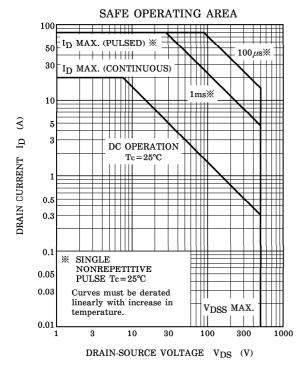
MARKING

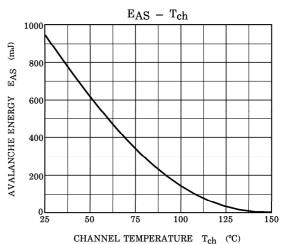


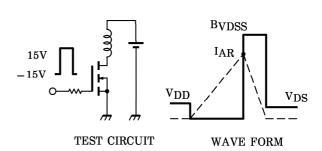












$$\begin{array}{l} \text{Peak I}_{AR} = 20\text{A, R}_{G} = 25\Omega \\ \text{V}_{DD} = 90\text{V, L} = 4.08\text{mH} \end{array} \\ \text{E}_{AS} = \frac{1}{2} \cdot \text{L} \cdot \text{I}^{2} \cdot \left(\frac{\text{B}_{VDSS}}{\text{B}_{VDSS} - \text{V}_{DD}} \right) \end{array}$$